

SEMITRANS[®] 3

Superfast IGBT Modules

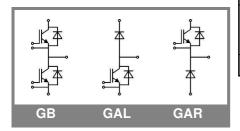
SKM 300GB063D SKM 300GAR063D SKM 300GAL063D

Features

- NPT- Non punch-through IGBT
- Low tail current with low temperature dependence
- High short circuit capability, self limiting if term. G is clamped to E
- Pos. temp.-coeff. of V_{CEsat}
- 50 % less turn off losses
- 30 % less short circuit current
- Very low C_{ies}, C_{oes}, C_{res}
- Latch-up free
- · Fast & soft inverse CAL diodes
- Isolated copper baseplate using DCB Direct Copper Bonding Technology without hard mould
- Large clearance (13 mm) and creepage distances (20 mm)

Typical Applications*

- Switching (not for linear use)
- Switched mode power supplies
- · AC inverter servo drives
- UPS uninterruptable power supplies
- · Welding inverters



Absolute Maximum Ratings $T_c = 25 ^{\circ}C$, unless otherwise specified								
Symbol	Conditions		Values	Units				
IGBT								
V_{CES}	T _j = 25 °C		600	V				
I _C	T _j = 150 °C	T _{case} = 25 °C	400	Α				
		T _{case} = 70 °C	300	Α				
I _{CRM}	I _{CRM} =2xI _{Cnom}		600	Α				
V_{GES}			± 20	V				
t _{psc}	V_{CC} = 300 V; $V_{GE} \le 20$ V; $V_{CES} < 600$ V	T _j = 125 °C	10	μs				
Inverse Diode								
I _F	T _j = 150 °C	T_{case} = 25 °C	250	Α				
		T _{case} = 80 °C	170	Α				
I _{FRM}	I _{FRM} =2xI _{Fnom}		600	Α				
I _{FSM}	$t_p = 10 \text{ ms; sin.}$	T _j = 150 °C	1600	Α				
Freewhee	eling Diode			•				
I_{F}	T _j = 150 °C	$T_c = 25 ^{\circ}C$	400	Α				
		$T_c = 80 ^{\circ}C$	270	Α				
I _{FRM}	I _{FRM} =2xI _{Fnom}		800	Α				
I _{FSM}	$t_p = 10 \text{ ms; sin.}$	T _j = 150 °C	2800	Α				
Module				•				
$I_{t(RMS)}$			500	Α				
T _{vj}			- 40 + 150	°C				
T _{stg}			- 40 + 125	°C				
V _{isol}	AC, 1 min.		2500	V				

Characteristics $T_c =$			25 °C, unless otherwise specified			
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_{C} = 6 \text{ mA}$		4,5	5,5	6,5	V
I _{CES}	$V_{GE} = 0 V, V_{CE} = V_{CES}$			0,2	0,6	mA
V_{CE0}		T _j = 25 °C		1,05		V
		T _j = 125 °C		1		V
r_{CE}	V _{GE} = 15 V	T _j = 25°C		3,2		mΩ
		T _j = 125°C		4,7		mΩ
V _{CE(sat)}	I _{Cnom} = 300 A, V _{GE} = 15 V	T _j = 25°C _{chiplev.}		2,1	2,5	V
		$T_j = 125^{\circ}C_{chiplev.}$		2,4	2,8	V
C _{ies}				17		nF
C _{oes}	$V_{CE} = 25, V_{GE} = 0 V$	f = 1 MHz		2		nF
C _{res}				1,2		nF
Q_G	V _{GE} = 0V+15V			720		nC
R _{Gint}	T _j = °C			0		Ω
t _{d(on)}				160		ns
t _r	$R_{Gon} = 6 \Omega$	V _{CC} = 300V		80		ns
E _{on}		I _C = 300A		14		mJ
t _{d(off)}	$R_{Goff} = 6 \Omega$	T _j = 125 °C		550		ns
t _f		$V_{GE} = \pm 15V$		50		ns
E _{off}				13		mJ
R _{th(j-c)}	per IGBT				0,09	K/W



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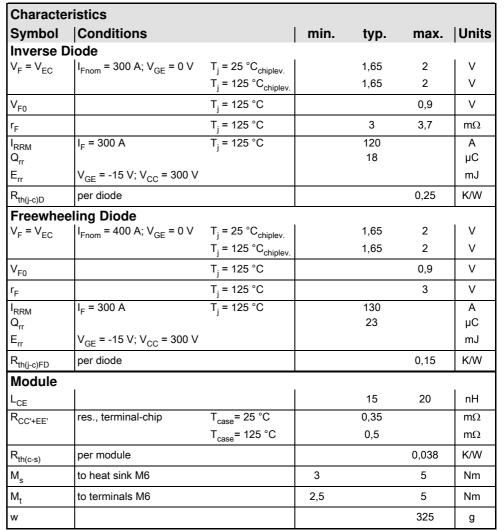
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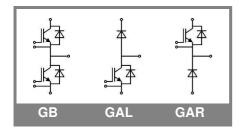
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This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.





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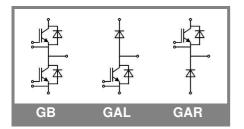
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Z _{th}			
Symbol	Conditions	Values	Units
${f Z}_{{\sf R_i}}$			
R _i	i = 1	65	mk/W
R_i	i = 2	19	mk/W
R_i	i = 3	4,7	mk/W
R_i	i = 4	1,3	mk/W
tau _i	i = 1	0,0518	s
tau _i	i = 2	0,0241	s
tau _i	i = 3	0,0021	s
tau _i	i = 4	0,0001	s
Z _{th(j-c)D}	<u> </u>		<u>.</u>
R _i	i = 1	140	mk/W
R_i	i = 2	85	mk/W
R_i	i = 3	20,55	mk/W
R_i	i = 4	4,45	mk/W
tau _i	i = 1	0,0613	s
tau _i	i = 2	0,0041	s
tau _i	i = 3	0,0045	s
tau _i	i = 4	0,0003	s

